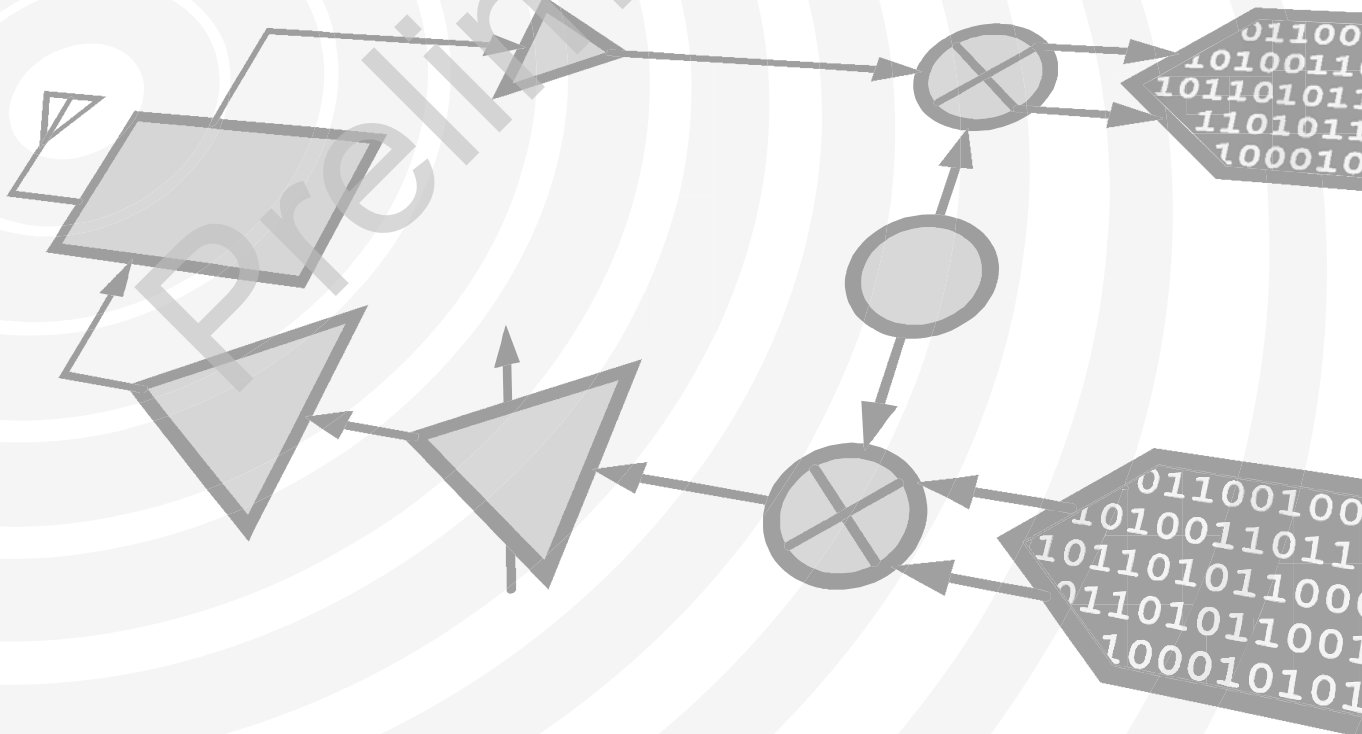


Analog Devices Welcomes Hittite Microwave Corporation



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Preliminary

HMC521ALC4

GaAs MMIC I/Q MIXER 8.5 - 13.5 GHz

Typical Applications

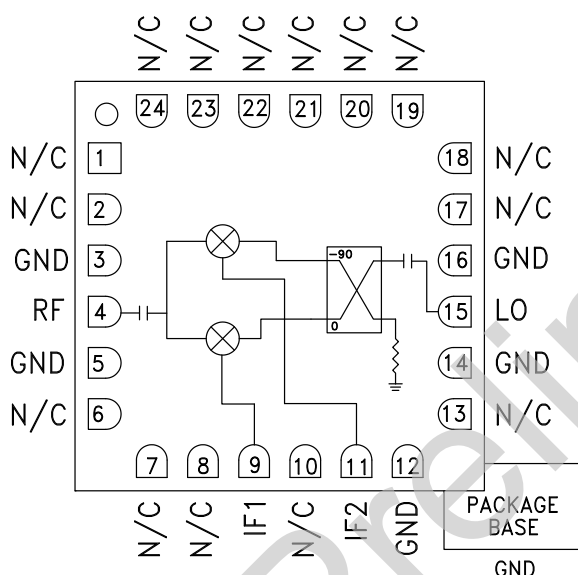
The HMC521ALC4 is ideal for:

- Point-to-Point and Point-to-Multi-Point Radio
- Military Radar

Features

- Wide IF Bandwidth: DC - 3.5 GHz
- Image Rejection: 38 dB
- LO to RF Isolation: 50 dB
- High Input IP3: +23 dBm
- 24 Lead 4x4mm SMT Package: 16mm²

Functional Diagram



General Description

The HMC521ALC4 is a compact I/Q MMIC mixer in a leadless "Pb free" RoHS compliant SMT package, which can be used as either an Image Reject Mixer or a Single Sideband Upconverter. The mixer utilizes two standard Hittite double balanced mixer cells and a 90 degree hybrid fabricated in a GaAs MESFET process. A low frequency quadrature hybrid was used to produce a 100 MHz USB IF output. This product is a much smaller alternative to hybrid style Image Reject Mixers and Single Sideband Upconverter assemblies. The HMC521ALC4 eliminates the need for wire bonding allowing use of surface mount manufacturing techniques.

Electrical Specifications, $T_A = +25^\circ\text{C}$, IF = 100 MHz, LO = +15 dBm*

| Parameter | Min. | Typ. | Max. | Min. | Typ. | Max. | Units |
|--------------------------|------|------------|------|-------------|------|------|-------|
| Frequency Range, RF/LO | | 8.5 - 13.5 | | 10.5 - 11.7 | | | GHz |
| Frequency Range, IF | | DC - 3.5 | | DC - 3.5 | | | GHz |
| Conversion Loss (As IRM) | | 8 | 10 | | 7.5 | 9.5 | dB |
| Image Rejection | 20 | 30 | | 30 | 38 | | dB |
| 1 dB Compression (Input) | | +14 | | | +15 | | dBm |
| LO to RF Isolation | 35 | 45 | | 45 | 55 | | dB |
| LO to IF Isolation | 18 | 22 | | 20 | 24 | | dB |
| IP3 (Input) | | +23 | | | +24 | | dBm |
| Amplitude Balance | | 0.3 | | | 0.1 | | dB |
| Phase Balance | | 4 | | | 4 | | Deg |

* Unless otherwise noted, all measurements performed as downconverter.

**GaAs MMIC I/Q MIXER
8.5 - 13.5 GHz**
Harmonics of LO

| LO Freq. (GHz) | nLO Spur at RF Port | | | |
|----------------|---------------------|----|----|----|
| | 1 | 2 | 3 | 4 |
| 8.5 | 42 | 44 | 44 | 70 |
| 9.5 | 50 | 53 | 59 | 77 |
| 10.5 | 51 | 54 | 63 | xx |
| 11.5 | 47 | 58 | 66 | xx |
| 12.5 | 45 | 59 | 70 | xx |
| 13.5 | 45 | 57 | xx | xx |

LO = +15 dBm
Values in dBc below input LO level measured at RF Port.

MxN Spurious Outputs

| mRF | nLO | | | | |
|-----|-----|----|----|----|----|
| | 0 | 1 | 2 | 3 | 4 |
| 0 | xx | -5 | 29 | 23 | 52 |
| 1 | 27 | 0 | 51 | 59 | 81 |
| 2 | 92 | 85 | 76 | 82 | 92 |
| 3 | 92 | 92 | 92 | 92 | 92 |
| 4 | 92 | 92 | 92 | 92 | 92 |

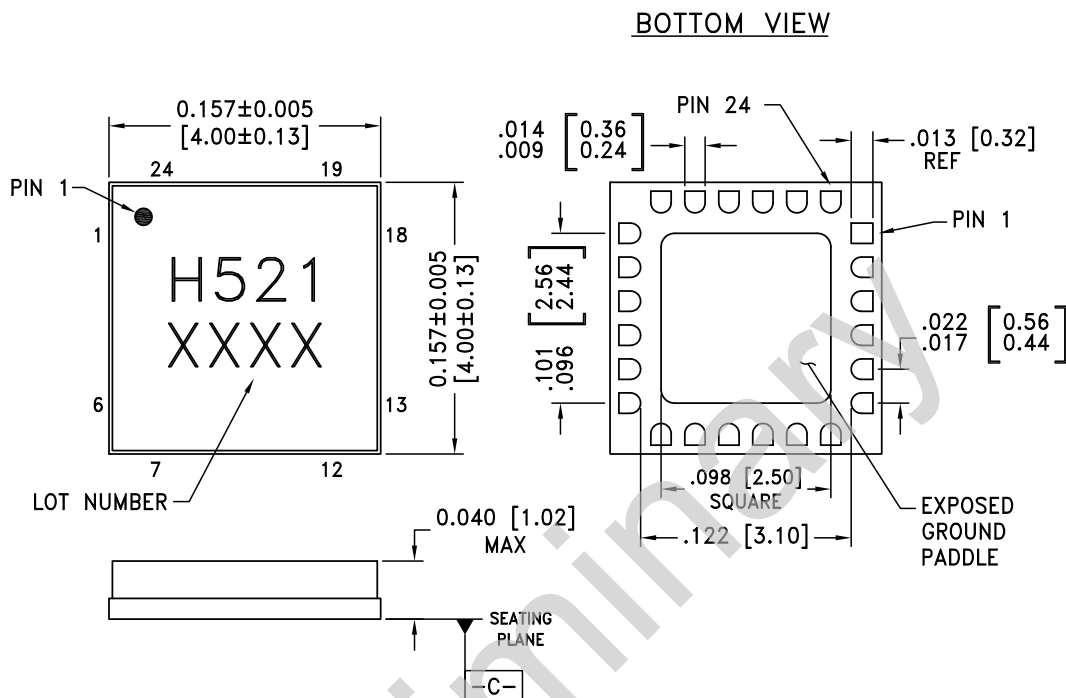
RF = 10.6 GHz @ -10 dBm
LO = 10.5 GHz @ +15 dBm
Data taken without IF hybrid
All values in dBc below IF power level

Absolute Maximum Ratings

| | |
|--|----------------|
| RF / IF Input | +20 dBm |
| LO Drive | +27 dBm |
| Channel Temperature | 150°C |
| Continuous P _{diss} (T=85°C) (derate 6.9 mW/°C above 85°C) | 460 mW |
| Thermal Resistance (R _{TH}) (junction to package bottom) | 141.4 °C/W |
| Storage Temperature | -65 to +150 °C |
| Operating Temperature | -55 to +85 °C |



**ELECTROSTATIC SENSITIVE DEVICE
OBSERVE HANDLING PRECAUTIONS**

Outline Drawing

NOTES:

1. PACKAGE BODY MATERIAL: ALUMINA
2. LEAD AND GROUND PADDLE PLATING: 30 - 80 MICROINCHES
GOLD OVER 50 MICROINCHES MINIMUM NICKLE
3. DIMENSIONS ARE IN INCHES [MILLIMETERS]
4. LEAD SPACING TOLERANCE IS NON-CUMULATIVE
5. PACKAGE WARP SHALL NOT EXCEED 0.05mm DATUM
6. ALL GROUND LEADS AND GROUND PADDLE MUST BE SOLDERED
TO PCB RF GROUND